

# A Truly Rugged I/O Platform







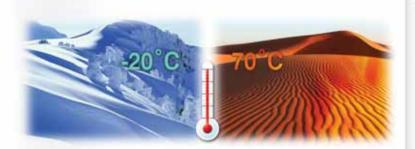
# Fanless

Fanless design significantly extends MTBF to 100,000 hours and minimizes the maintenance cost.



# Rugged

The Matrix is designed to operate in a -20 to 70°C wide temperature range and withstand up to 100 G shock and 5 G vibration, making it ideal for deployment in harsh environments.



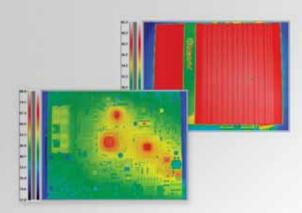
# Application-specific

By integrating ADLINK DAQ, DIO, motion and vision technologies, the Matrix can provide specific I/O functions on-board for your applications.



# Sophisticated Design of the Matrix

## Comprehensive Consideration for Heat Dissipation



Mechanical and electrical engineers worked from the early design stages of the Matrix to ensure the best performance of conductive heat dissipation. All components, such as the CPU, chipset, memory, clock generator, MOSFET, and power choke, etc. generate heat and are thus placed on the top of the PCB and kept at a minimal pitch from the aluminum case. Thus we can provide the shortest path of heat conduction and lowest thermal resistance to guarantee the thermal stability of the Matrix at a 70°C ambient temperature.

# ■ Cable-less and User-friendly Mechanical Structure



The Matrix features an excellent cable-less design. All components and connectors are directly mounted on the PCB via SMT and DIP processes instead of cable connections. The result is an extremely strong and durable mechanical structure suitable for the harshest of environments with 5 Grms vibration and up to 100 G shock and vibration. The Matrix MXC-2000 series—being a configurable controller—also provides a very user-friendly design for system installation. You can open the chassis and install your PCI/PCIe card simply by loosening screw. And, only four screws are used to install or replace the hard disk drive. The mechanical design provides the best reliability, durability and easiest access for installation and maintenance.

## ■ Wide Range and Reliable DC Power Input



We know you may need to deploy the Matrix anywhere. So, we designed the Matrix with wide range DC input to allow it to be powered everywhere. Regardless if there is 12 or 24 volts available at the site, or you have a 19 V laptop adapter handy, you can simply feed the electricity into the MXE-1000 series (6-36 VDC) or MXC-2000 series (9-32 VDC) and it will run. The Matrix is also ideal for use with solar power because of the great tolerance for the variation of solar panel output. The power circuitry of the Matrix was carefully designed with high-quality components (regulators, capacitors, and inductors) to supply reliable power under almost any circumstances.

6

Remote I/O

10

12

Accessories

# **Matrix MXE-1000 Series**

## Intel® Atom™ Fanless Embedded Controller with Integrated I/O



### Features

Intel® Atom™ N270 I.6 GHz processor + 945GSE chipset Rugged, -20°C to 70°C fanless operation Built-in 6 VDC to 36 VDC wide-range DC power input Up to three I000/I00/I0 Mbps Ethernet ports Two 1394b FireWire ports (MXE-1020 only) Two RS-232 ports and two RS-232/422/485 ports One internal PCIe Mini Card socket with an USIM socket One external CF socket

### **Applications**

**Intelligent Transportation Facility Management Environment Monitoring Machine Automation** Video Surveillance/Recognition **Building Automation** 



Inside MXE-1000 Series

### Introduction

ADLINK's MXE-1000 series is an exceptionally rugged embedded controller for operating in harsh environments. Its -20 to 70°C temperature range allows it to operate outdoors in both hot summer days and cold winter nights. The Matrix can also be deployed in factory planes or on vehicles as it can withstand 5 Grms vibration. And, its fanless and cable-less structure ensures extensive durability for long-term usage.

The Matrix MXE-1000 series features the Intel® Atom™ N270 1.6 GHz processor to deliver adequate performance at low-power. The MXE-1000 also integrates versatile generic and special-purpose I/O features to support a wide variety of applications. The on-board Gigabit Ethernet and 1394b ports are designed for connecting cameras for surveillance and image recognition applications, while its COM ports fit requirements in most machine automation and facility management applications.

Combing rugged design and integrated I/O functions, the ADLINK MXE-1000 series offers the most versatile choice for your applications.



MXF-1000 Series Front Panel



MXE-1005 Back Panel



MXE-1010 Back Panel



MXE-1020 Back Panel

шхрипогот

6 AC

7

1011011

Real-time Distributed I/O

/U

Remote I/O

10

Communications

VISION

12
Fanless I/O

iationnis

13

Industrial Computer

14

Accessories

# **Specifications**

Model Name	MXE-1005	MXE-1005 MXE-1010				
System Core						
Processor		Intel® Atom™ N270 I.6 GHz CPU				
Chipset		ntel® 945GSE Graphic Memory Control Hub ntel® I/O Controller Hub 7 Mobile (ICH7-M)				
Video	Analo	g CRT, supports QXGA (2048 x 1536) Resolu	ution			
Memory		I GB DDR2 533 MHz SODIMM module				
I/O Interface						
Ethernet	Ix GbE port (Realtek® 8111C)	3x GbE ports (Realtek® 8111C+Intel® 82574) (support teaming function)	Ix GbE port (Realtek® 8111C)			
1394b	-	-	2x 1394b FireWire 800 Ports			
Serial Port	2x RS-	232/422/485 (jumper selectable, COM1 & CO 2x RS-232 (COM3 & COM4)	OM2)			
USB		4x USB 2.0 Ports				
Mini-PCle		Ix Internal PCIe Mini Card Socket				
SIM	Ix USIM Socke	Ix USIM Socket for 3G Communication (used with 3G Mini-PCle Module)				
Audio		Ix Mic-in and Ix Speaker-out				
KB/MS	Ix PS/2 Keyboard and Ix PS/2 Mouse					
Power Supply						
DC Input	Built-in 6-36 VDC Wide-range DC input					
	3P Pluggable Connector with Latch (V-, GND, V+)					
AC Input	Optional 40 W External AC-DC Adapter for AC input					
Storage Device						
SATA HDD	On-board SATA Port for 2.5" HDD/SSD Installation					
CompactFlash	I x Ty	pe I CF Socket, Supporting PIO and DMA Mo	odes			
Mechanical						
Dimensions		210 mm (W) x 170 mm (D) x 53 mm (H)				
Weight		1.8 kg (3.96 lbs)				
Mounting		VESA 100 Wall Mounting Kit				
Environmental						
Operating Temperature	Standard: -10°C to 60°C Extended option: -20°C to 70°C					
Storage Temperature		-40°C to 85°C (excluding HDD/SSD/CF)				
Humidity		~95% @ 40°C (non-condensing)				
Vibration	·	rating, 5 Grms, 5-500 Hz, 3 Axes (w/ CF or S erating, 0.7 Grms, 5-500 Hz, 3 Axes (w/ HDI	,			
Shock		, 100 Grms, Half-sine 11 ms Duration (w/ CF				

# Ordering Information

Model Name	CPU	GbE	1394b	СОМ	USB	Memory
MXE-1005	Intel® Atom™ N270 fanless embedded controller	I		4	4	I GB DDR2
MXE-1010	Intel® Atom™ N270 fanless embedded controller	3		4	4	I GB DDR2
MXE-1020	Intel® Atom™ N270 fanless embedded controller	1	2	4	4	I GB DDR2

# **Optional Accessories**

2 GB DDR2 Upgrade	Upgrade to 2 GB DDR2 Memory
160 GB HDD Option	Factory-installation of 160 GB SATA Hard Disk Drive (0 to 50°C)
32 GB SSD Option	Factory-installation of 32 GB SATA Solid State Disk (0 to 70°C)
8 GB Industrial SSD Option	Factory-installation of 8 GB Industrial-grade SATA Solid State Disk (-40 to 85 $^{\circ}\text{C})$
40 W AC Adapter	40W Industrial-grade AC Adapter (-20 to 70°C)
Extended Temperature Option*	Extend the operating temperature of the MXE-1000 series to -20 to $70^{\circ}\text{C}$

 $<sup>^{\</sup>star}\text{This}$  option guarantees cold boot of the system at -20  $^{\circ}\text{C}$  and operation with 100% loading at 70  $^{\circ}\text{C}$ 

# **Matrix MXC-2000 Series**

### Intel® Atom™ Fanless Configurable Controller with PCI/PCIe Slots



Features

Intel® Atom™ N270 I.6 GHz processor + 945GSE chipset Configurable, providing both PCI and PCIe slot options

Rugged, -20°C to 70°C fanless operation

Built-in 9 VDC to 32 VDC wide-range DC power input

Dual 1000/100/10 Mbps Ethernet ports

Two RS-232 ports and two RS-232/422/485 ports

Two CF sockets for HDD replacement and hot-swappable data storage

VGA + S-Video independent dual display outputs

Optional on-board 16-CH isolated DI and 16-CH isolated DO

### **Applications**

**Industrial Automation Factory Control** Test Instrumentation Security Surveillance **Data Acquisition System** 

**Building Automation** 



Easy Installation for HDD and PCI/PCIe Cards

### Introduction

ADLINK's MXC-2000 series is an exceptionally rugged controller with configurable PCI and PCIe slots. It is designed to provide a reliable platform for a wide variety of applications by accepting standard PCI and PCIe cards. The Matrix MXC-2000 series can operate in a -20 to 70°C temperature range and withstands 5 Grms vibration. Its fanless and cable-less structure provides additional durability for long-term usage.

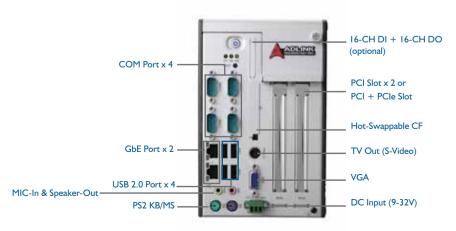
The Matrix MXC-2000 series features the Intel® Atom™ N270 I.6 GHz processor to deliver adequate performance at low power. Its PCI and PCIe slots enable the possibility of integrating off-the-shelf PCI/PCIe cards for a configurable application platform. Generic I/O interfaces, such as Gigabit Ethernet, COM, and USB are provided for connecting devices, while VGA+S-Video dual graphic outputs to allow connections to larger displays such as an LCD TV. The Matrix MXC-2000 series also integrates ADLINK in-house DIO design to deliver optional isolated DIO channels for industrial control usage.

ADLINK's Matrix MXC-2000 series is the perfect combination of configurability, reliability, durability, and compactness. With the MXC-2000 series, creating your rugged application system has never been easier.





Inside MXC-2000 Series



MXC-2000 Series Front Panel

Software &

ftware & ilities

2

DAQ

3

1 7.1

ladular.

struments

GPIB & Bus Expansion

Expunsion

6

lotion

3

ear-time istributed O

9)

Remote I/O

10

Communications

11

VISION

12

Platforms

13

cPCI & Industrial Computer

14

ı	_	c	_			_	,		c
١	b	b	U	o	0	U		!	C

# **Specifications**

Model Name	MXC-2002	MXC-2011			
System Core					
Processor	Intel®Atom™ N	270 I.6 GHz CPU			
Chipset	Intel® 945GSE Graphi	ic Memory Control Hub			
	Intel® I/O Controller	Hub 7 Mobile (ICH7-M)			
Video	Analog CRT, Supports QX	GA (2048 x 1536) Resolution			
	TV-out, Supports S-Vide	o and Composite Outputs			
Memory	I GB DDR2 533 MHz SODIMM module				
I/O Interface					
Expansion Slots	Two PCI slots	One PCI slot and one x1 PCIe slot			
Ethernet	2x GbE Ports (	(Realtek® 8111C)			
Serial Port	2x RS-232/422/485 (jumper	selectable, COM1 & COM2)			
		OM3 & COM4)			
USB		2.0 Ports			
Audio	Ix Mic-in and Ix Speaker-out				
KB/MS	Ix PS/2 Keyboard and Ix PS/2 Mouse				
DIO	Optional 16-CH isolated	d DI + 16-CH isolated DO			
Power Supply					
DC Input		vith Over-voltage Protection with Latch (GND, V-, V+)			
AC Input	Optional 60W external A	C-DC adapter for AC input			
Storage Device					
SATA HDD	On-board SATA Port for 2.5" HDD/SSD Installation				
CompactFlash	2x Type II CF Sockets, Supporting PIO and DMA Modes				
	CFI (internal) for HDD Replacement				
	CF2 (external) Supports Hot-swapping				
Mechanical					
Dimensions	118 mm (W) x 219 r	mm (D) x 183 mm (H)			
Weight	2.8 kg	(6.16 lbs)			
Mounting	Wall-m	nount Kit			
Environmental					
Operating Temperature		10°C to 60°C on: -20°C to 70°C			
Storage Temperature	-40°C to 85°C (exc	luding HDD/SSD/CF)			
Humidity	`	(non-condensing)			
Vibration	Operating, 5 Grms, 5-500	0 Hz, 3 Axes (w/CF or SSD) -500 Hz, 3 Axes (w/HDD)			
Shock		e II ms duration (w/CF or SSD)			

# Ordering Information

Model Name	Description	PCI	xI PCle	GbE	СОМ	USB	Memory	DIO
MXC-2002	Intel® Atom™ N270 fanless configurable controller	2	0	2	4	4	I GB DDR2	
MXC-2002D	Intel® Atom™ N270 fanless configurable controller	2	0	2	4	4	I GB DDR2	16 DI+16 DO
MXC-2011	Intel® Atom $^{\scriptscriptstyleTM}$ N270 fanless configurable controller	I	I	2	4	4	I GB DDR2	
MXC-2011D	Intel® Atom™ N270 fanless configurable controller	1	1	2	4	4	I GB DDR2	16 DI+16 DO

## **Optional Accessories**

-	
2 GB DDR2 Upgrade	Upgrade to 2 GB DDR2 Memory
160 GB HDD Option	Factory-installation of 160 GB SATA Hard Disk Drive (0-50°C)
32 GB SSD Option	Factory-installation of 32 GB SATA Solid State Disk (0-70°C)
8 GB Industrial SSD Option	Factory-installation of 8 GB Industrial-grade SATA Solid State Disk (-40 to 85°C)
60 W AC Adapter	60 W Industrial-grade AC adapter (-20 to 70°C)
Extended Temperature Option*	Extend the operating temperature of the MXC-2000 series to -20 to $70^{\circ}\text{C}$



### **ADLINK DPAC Features**

### **Compact & Fanless Design**

The DPAC is a small (162 x 150 x 50 mm) distributed PC-based controller platform. The DPAC system incorporates a fanless design and optimal heat sink dissipation to ensure the operational reliability and stability.



### High Tolerant Vibration and Shock Capability

Designed for industrial automation applications, the DPAC underwent harsh vibration and shock testing during its design to ensure durability. While in operation, the DPAC can tolerate shocks of up to 100 G and vibrations of up

### Smart UI with Programmable Buttons and a Digital Display

One key feature of a DPAC system is the digital display and programmable button design. Compact computers can be easily found, but finding a PC-based controller platform that is both compact and reliable is another story. ADLINK's DPAC solution meets a wider variety of application requirements than standard compact computers by providing a digital display can be programmed to provide information and buttons that can be assigned to a controller task.

Programmable digital display and buttons for a flexible design -



### **Function Extension by Distribution**

Functional control blocks can be distributed via the fieldbus or serial communication ports depending on the configuration of the DPAC. This greatly reduces the wiring of the entire system whereas compact industrial computers typically require excessive and expensive wiring.

### Flexible Integrated Development Platform

Modules such as digital I/O, AD/DA devices, relay switch controls, thermocouple inputs, and motion controllers can be connected together and communicated to via the fieldbus or serial communication ports. If a fast and time deterministic response is needed, the DPAC provides HSL and Motionnet fieldbuses to achieve such performance requirements. The distributed nature of the DPAC means that all the functional blocks can be installed near the sensors, actuators, servo motors, etc.

### **Standard Programming Environment**

ADLINK's DPAC supports IEC 61131-3 languages: LD (Ladder Diagram), FBD (Function Block Diagram), ST (Structural Text), IL (Instructional Language), and SFC (Sequential Flow Chart). By using these standard languages, software can be developed for the DPAC easier and quicker than with PC-based controller platforms.

### **External GPIO as Trigger Signal**

The DPAC is equipped with a 4-CH external GPIO. These GPIO signals can be used as triggers to synchronously control other devices.



162



Vertical and wallmount designs

Vibrarion tolerance up to  $5\ G$  (operational)

Shock tolerance up to 100 G (operational)



### Ordering Information

DPAC-I0X0-ZN Intel® Atom™ N270 CPU with 4 COM ports	
217.0 107.0 217	
DPAC-30Y0-ZN Intel <sup>®</sup> Atom <sup>™</sup> N270 CPU with HSL & Motionnet Bus	

Model Name	Description
Accessories	
General-purpose I/O cable	I M length cable with single-end open wire
Li battery	CR2032 type battery for data backup protection
Industrial-grade CF	4 GB storage for DPAC external slot

COM2	COM3	COM4
RS-232	RS-232	RS-232
RS-232	RS-232	RS-422
RS-232	RS-232	RS-485
RS-232	RS-422	RS-422
RS-232	RS-422	RS-485
RS-232	RS-485	RS-485
RS-422	RS-422	RS-422
RS-422	RS-422	RS-485
RS-422	RS-485	RS-485
RS-485	RS-485	RS-485
	RS-232 RS-232 RS-232 RS-232 RS-232 RS-232 RS-422 RS-422 RS-422	RS-232 RS-232 RS-232 RS-232 RS-232 RS-232 RS-232 RS-422 RS-232 RS-422 RS-232 RS-485 RS-422 RS-422 RS-422 RS-422 RS-422 RS-422

Υ	COM2
0	RS-485
1	RS-422
2	RS-232

Z	OS Language Support
- 1	Windows XP Embedded (English)
2	Windows XP Embedded (Traditional Chinese)
3	Windows XP Embedded (Simplified Chinese)
4	Windows XP Embedded (Japanese)
5	Windows XP Embedded (Korean)

Software &

oftware & tilities

4

2710

PXI

1

Modular Instruments

5

GPIB & Bus Expansion

6

PAC

7

Motion

8

Real-time Distributed I/O

9

Remote I/O

10

Communications

11

Vision

12

anless I/O Platforms

13

cPCI & Industrial Computers

14

Accessories



Distributed Programmable Automation Controller with Four COM Ports (Intel® Atom $^{\text{\tiny TM}}$  N270 I.6 GHz CPU)

Support RS-232/RS-422/RS-485







### **Specifications**

Model Number		DPAC-1000-1N	DPAC-1000-11	
System	CPU	Intel <sup>®</sup> Atom™ N270, FSB 533, I.6 GHz		
Hardware	Cache	512 KB L2 cache		
	System Memory	I GB DDR2 SDRAM		
	Battery Backup SRAM	512 KB, battery model: CR2032 (Recommended)		
	BIOS	Award BIOS, support PnP, customized by ADLINK		
	Programmable Button	4 (Specifc function can be programmed by users)		
	Digital Display	5 digits, user programmable		
	Internal Storage	CompactFlash, 4 GB		
	External Storage	CompactFlash Type I, optional		
	VGA	CRT: 2048 x 1536 resolution @ 70 Hz (QXGA);		
		LCD: Single or dual channel 18-bit TFT with resolution		
		from 640 x 480 (VGA) u	from 640 x 480 (VGA) up to $1600 \times 1200$ (UXGA)	
	Watchdog Timer	Programmable timer ranges to generate RESET		
	GPIO	4 DI/4 DO onboard (Support o	4 DI/4 DO onboard (Support one 32-bit counter up to 20 KHz)	
	Keyboard/Mouse	Combined PS/2 type	PS/2 type mini-DIN connectors	
Communication	USB	2 USB ports, rev 2.0 compliant		
	Ethernet	Dual LAN, 10/100 Base-T RJ-45 ports		
	COM Port	COMI supp	COM1 supports RS-232;	
		COM2 supports RS-232/RS-422/RS-485 with DB-9 connectors (RS-485 with auto data flow control);		
		COM3 and COM4 support RS-232/RS-422/RS-485 with RJ-45 connectors (RS-485 with auto data flow control)		
Environment	Humidity	95% @ 60°C		
	Operating Temperature	0 - 60°C @ 9	0 - 60°C @ 5% - 85% RH	
	Vibration Protection (In Operation Test)	IEC 68 2-64 (Random 3 axes, 30 min/axis) CompactFlsh: 5 Grms @ 5 - 500Hz		
	Shock Protection (In Operation Test)	IEC 68 2-27 CompactFlsh: 100 G @ wall mount, half sine, 11 ms		
General	Certification	CE/FCC	CE/FCC Class A	
	Mounting	Wall mounting, vertical placement		
	Power Input	10 $V_{DC}$ - 30 $V_{DC}$ , 2.55 A, 30 W with 3-pin connector		
	Power Consumption	30 W (Typical), Isolation		
	Dimensions	162 mm (H) x 150 mm (D) x 50 mm (W) (Vertical placement)		
	Embedded OS	Windows® XP Embedded (English Version)		
	CoDeSys (SoftPLC) Run Time	No	Yes	



Distributed Programmable Automation Controller with HSL and Motionnet Buses (Intel $^{\text{\tiny{M}}}$  Atom $^{\text{\tiny{TM}}}$  N270 I.6 GHz CPU)







## **Specifications**

Model Number		DPAC-3000-IN	DPAC-3000-11	
System	CPU	Intel® Atom™ N270, FSB 533, 1.6 GHz		
Hardware	Cache	512 KB L2 cache		
	System Memory	I GB DDR2 SDRAM		
	Battery Backup SRAM	264 Kb, battery model: CR2032 (Recommended)		
	BIOS	Award BIOS, support PnP, customized by ADLINK		
	Programmable Button	4 (Specifc function can be programmed by users)		
	Digital Display	5 digits, user programmable		
	Internal Storage	CompactFlash, 4 GB		
	External Storage	CompactFlash Type I, optional		
	VGA	CRT: 2048 x 1536 resolution @ 70 Hz (QXGA);		
		LCD: Single or dual channel 18-bit TFT with resolution from		
		640 x 480 (VGA) up to 1600 x 1200 (UXGA)		
	Watchdog Timer	Programmable timer ranges to generate RESET		
	HSL Bus (Distributed I/O) (Step Technica)	One port support 12M/6M/3M bps full duplex		
	Motionnet Bus (Distributed Motion) (NPM)	One port support 20M bps (Max.)		
	GPIO	4 DI/4 DO onboard (Support one 32-bit counter up to 20 KHz)		
	Keyboard/Mouse	Combined PS/2 type mini-DIN connectors		
Communication	USB	2 USB ports, rev 2.0 compliant		
	Ethernet	Dual LAN, 10/100 Base-T RJ-45 ports		
	COM Port COMI supports RS-232; COM2 supports RS-232/RS-422/RS-485		supports RS-232/RS-422/RS-485	
		with DB-9 connectors (RS-485	with auto data flow control)	
Environment	Humidity	95% @ 60°C		
	Operating Temperature	0 - 60°C @ 5% - 85% RH		
	Vibration Protection (In Operation Test)	IEC 68 2-64 (Random 3 axes, 30 min/axis)  CompactFlsh: 5 Grms @ 5 - 500Hz		
	Shock Protection (In Operation Test)	IEC 68 2-27 CompactFlsh: 100 G @ wall mount, half sine, 11 ms		
General	Certification	CE/FCC Class A		
	Mounting	Wall mounting, vertical placement		
	Power Input	10 V <sub>DC</sub> - 30 V <sub>DC</sub> , 2.55 A, 30 W with 3-pin connector		
	Power Consumption	30 W (Typical), Isolation		
	Dimensions	162 mm (H) $\times$ 150 mm (D) $\times$ 50 mm (W) (Vertical placement)		
	Embedded OS	Windows® XP Embedded (English version)		
	CoDeSys (SoftPLC) Run Time	No	Yes	

1

Software a

2

DAQ

3

PXI

4

Modular Instruments

5

GPIB & Bus Expansion

6

PAC

7

Vlotion

oal time

istributed 0

9

Remote I/O

10

Communications

77-7

Vision

Vision

12

anless I/O Platforms

70

13

cPCI & Industrial Computers

14

Accessories